

November 17, 2003

TO: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Attn: **Mail Stop Missing Parts**

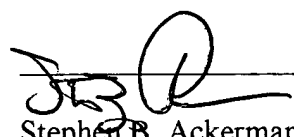
FROM: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, NY 12603

Subject: Serial #:10/638,235  
File Date:8/8/03  
Invr(s): Li, C., et al  
Title: Method to Form Copper Seed Layer For Copper Interconnect

**RESPONSE TO FILE CORRECTED APPLICATION PAPERS**

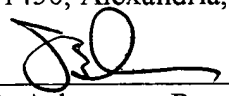
Sir:

In response to the NOTICE TO FILE CORRECTED APPLICATION PAPERS, dated November 6, 2003, it was stated that the drawings submitted are not acceptable because they must be reasonably free from erasures and must be free from alterations, overwriting, interlineations, folds, and copy marks. The replacement drawings are hereby enclosed.

  
\_\_\_\_\_  
Stephen B. Ackerman  
Reg. No. 37,761

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patent, P.O. Box 1450, Alexandria, VA 22313-1450 on November 17, 2003.

Signature   
\_\_\_\_\_  
Stephen B. Ackerman, Reg. No. 37,761

Date: 11/17/03

It is requested that should there be any further questions to please call the undersigned Attorney at (845) 452-5863.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'StB. Ackerman', with a large, stylized 'Q' or 'O' shape at the end.

Stephen B. Ackerman  
Reg. No. 37,761

Attached: Replacement drawings